

Fig. 1

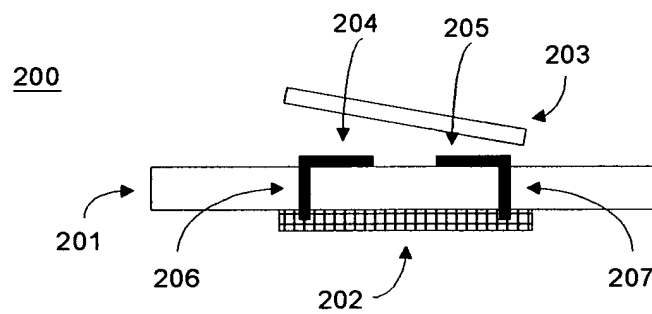


Fig. 2

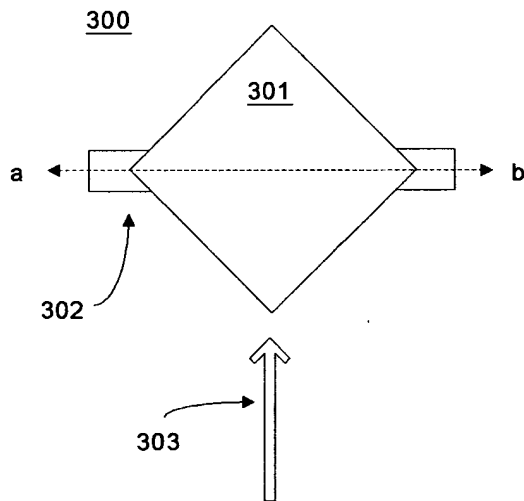


Fig. 3A

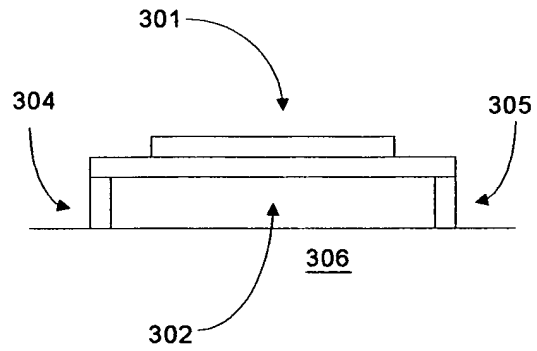


Fig. 3B

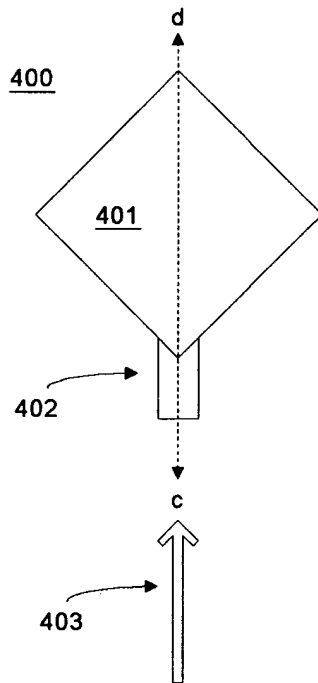


Fig. 4A

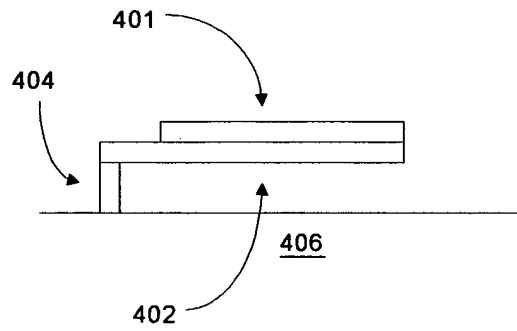


Fig. 4B

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Serial No.: Not yet assigned
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Docket No.: Fishii001

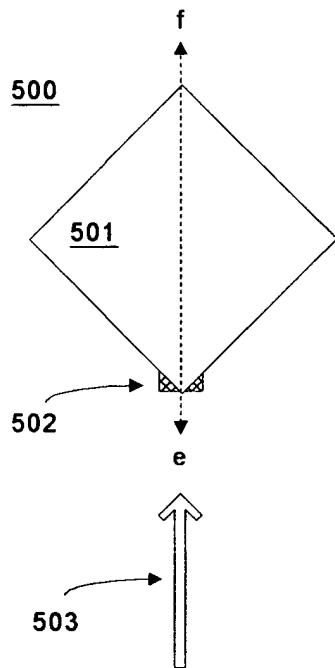


Fig. 5A

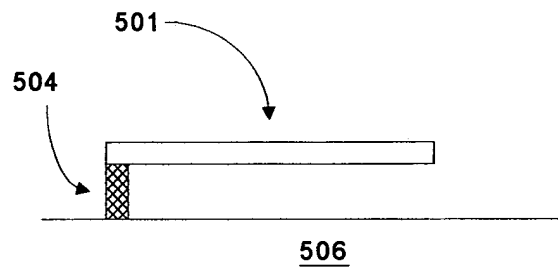
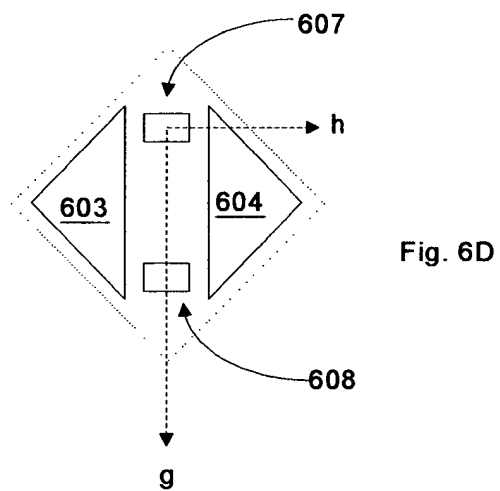
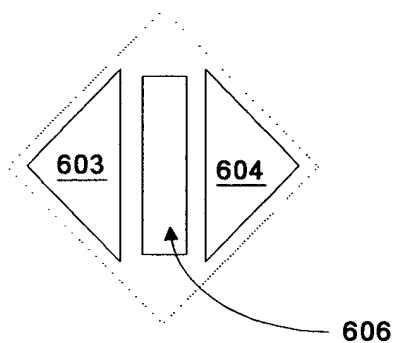
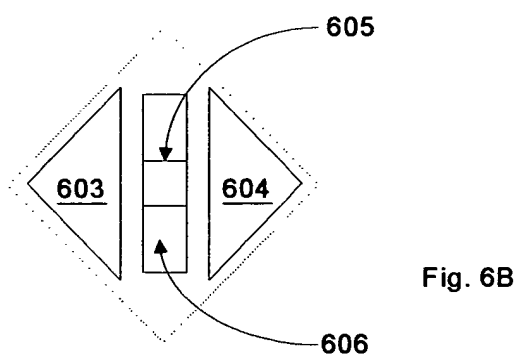
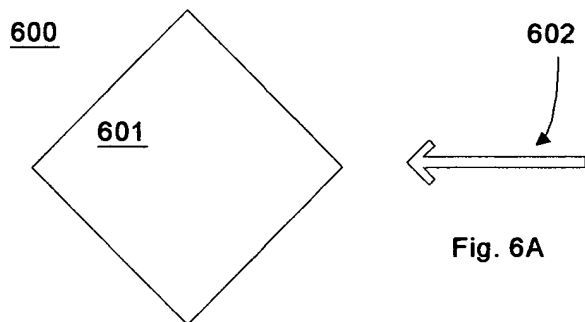


Fig. 5B



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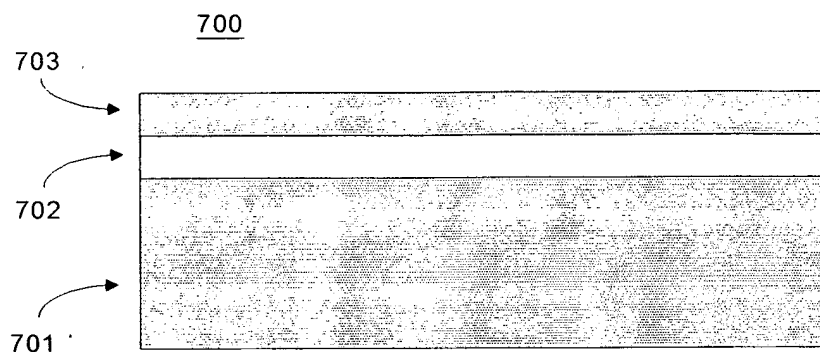


Fig. 7A

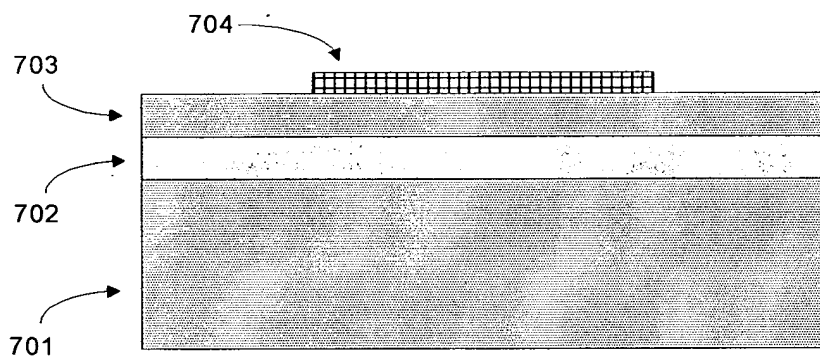


Fig. 7B

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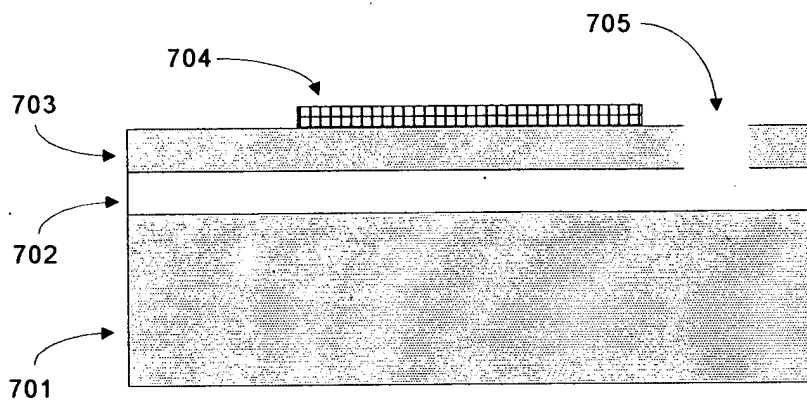


Fig. 7C

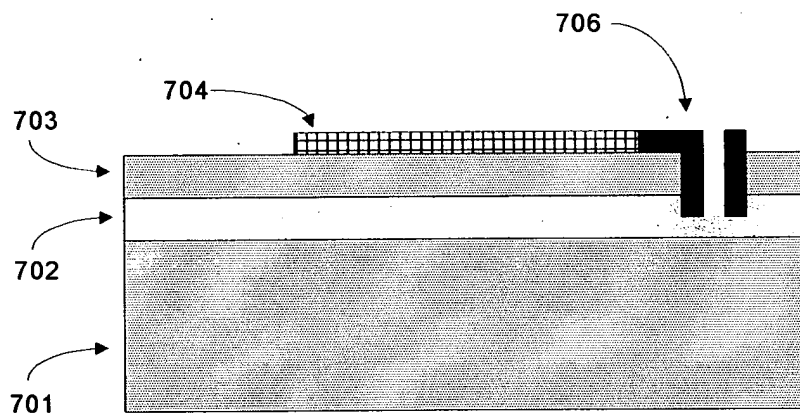


Fig. 7D

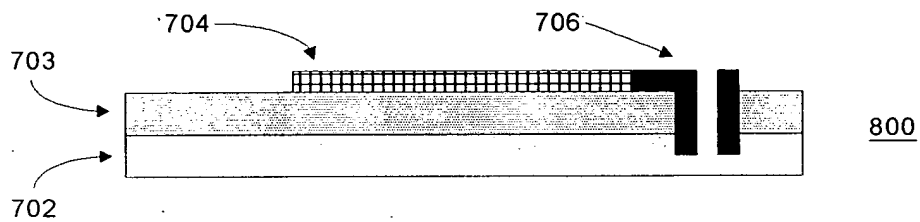


Fig. 8A

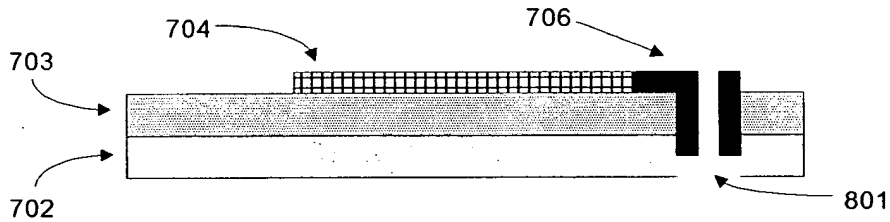


Fig. 8B

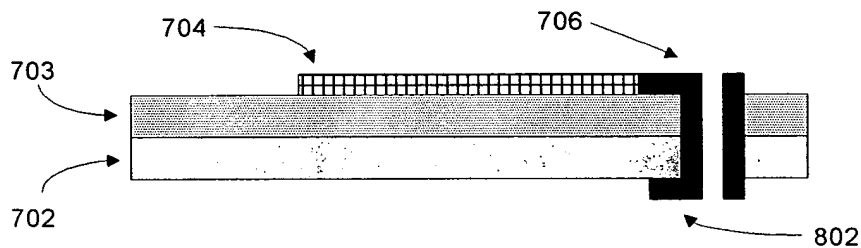


Fig. 8C

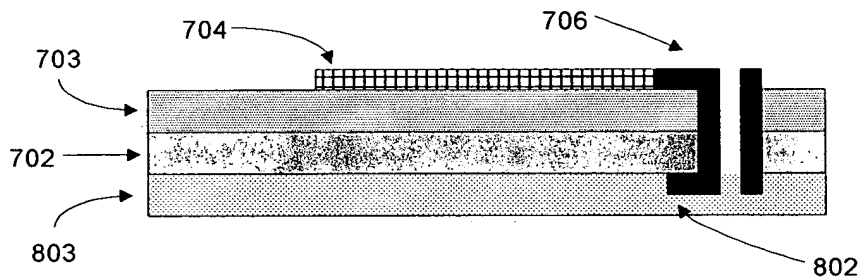


Fig. 8D

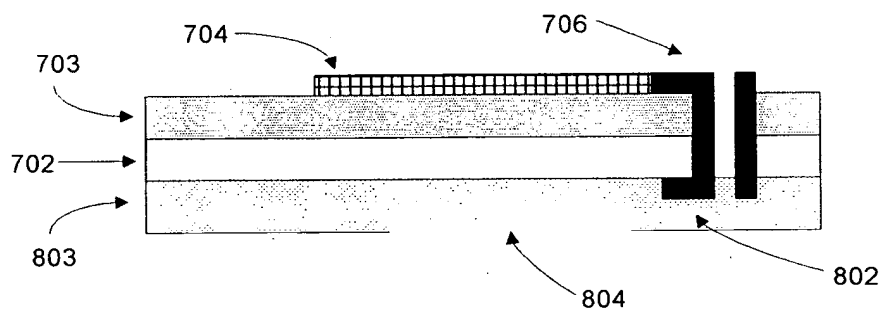


Fig. 8E

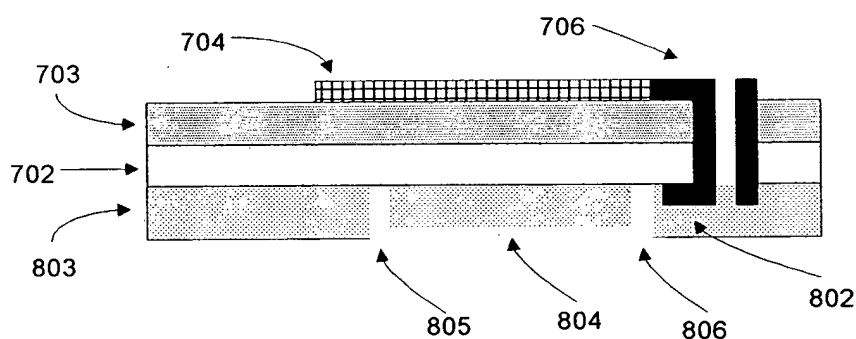


Fig. 8F

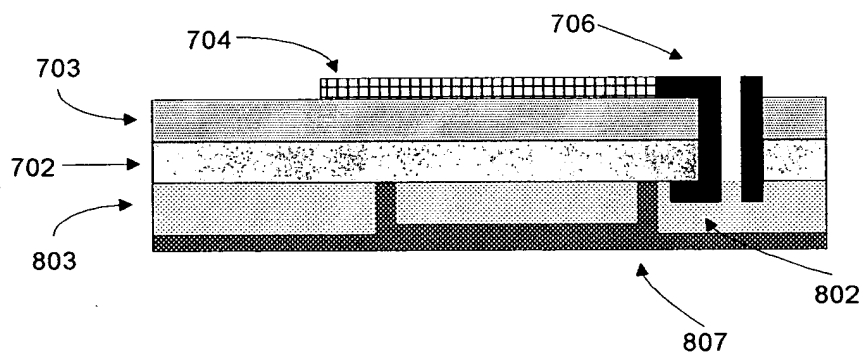


Fig. 8G

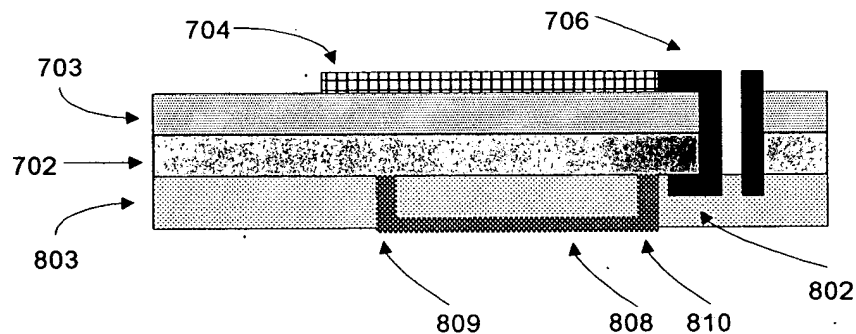


Fig. 8H

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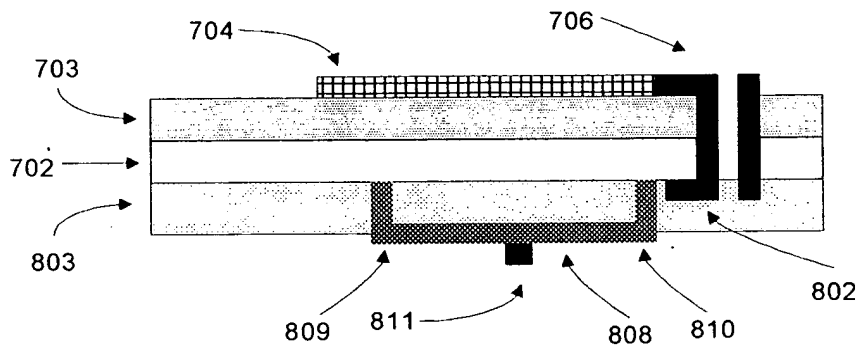


Fig. 8I

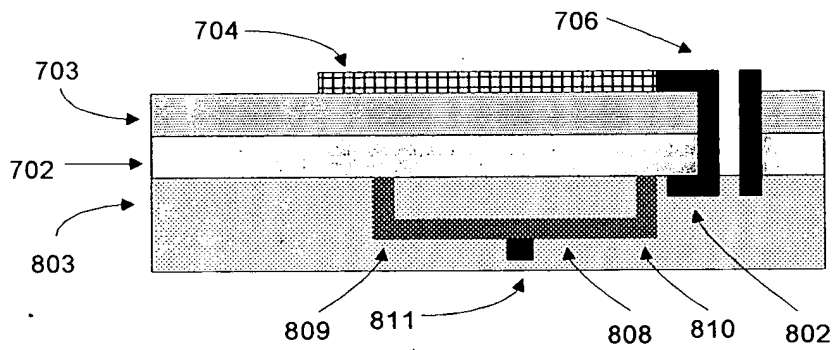


Fig. 8J

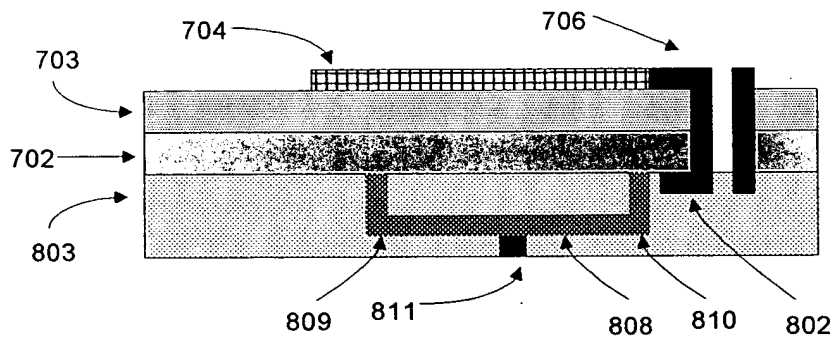


Fig. 8K

A cross-sectional view of a semiconductor device. The device consists of a substrate 802 with a bottom layer 812. A central region contains a stack of layers: a bottom layer 803, a middle layer 702, and a top layer 703. A patterned layer 704 is on top of layer 703. A thick, dark, U-shaped layer 706 is positioned on the right side of the device, partially covering the top layer 703 and the middle layer 702.

A cross-sectional view of a device assembly. A horizontal substrate 702 is shown with a thin layer 703 on its top surface. A grid-like structure 704 is positioned on top of layer 703. A thick, dark, L-shaped component 706 is attached to the right side of the substrate 702. Below the substrate, a U-shaped component 812 is positioned, and a thick, dark, T-shaped component 802 is positioned below the U-shaped component 812. Arrows point from the labels to their respective components.

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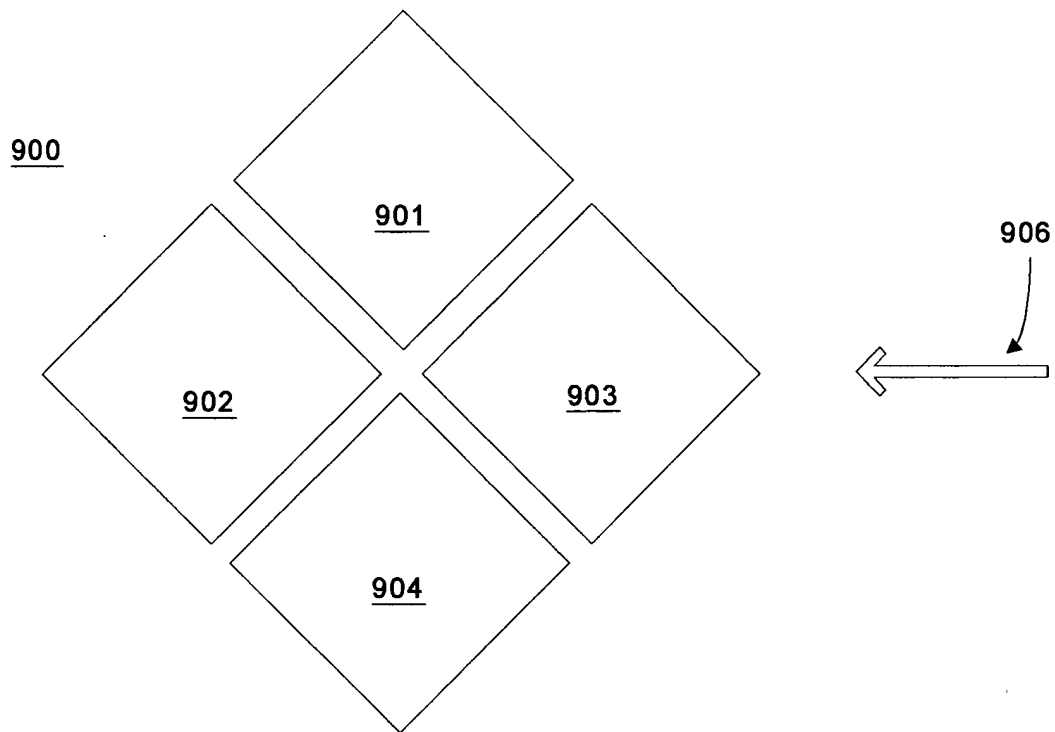


Fig. 9

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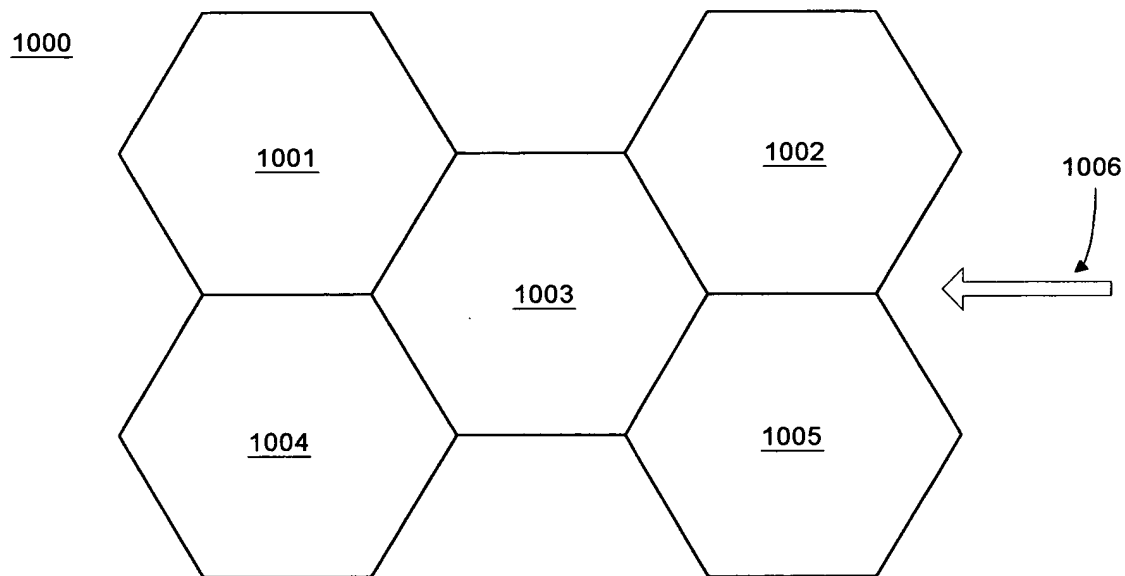


Fig. 10

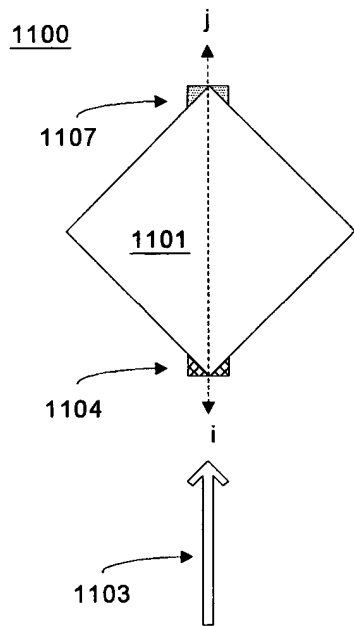


Fig. 11A

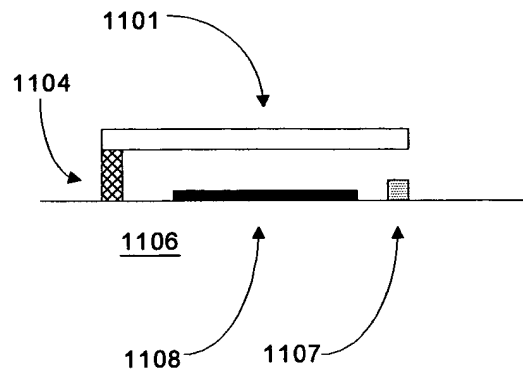


Fig. 11B

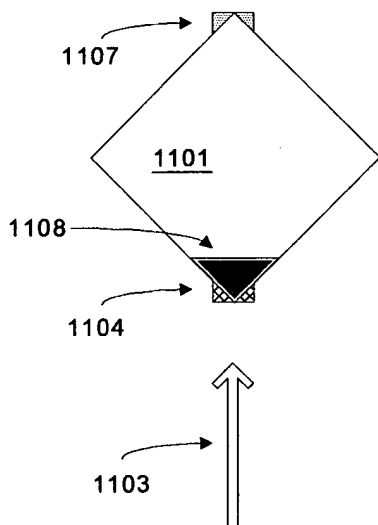


Fig. 11C